GaN on SiC HEMT Pulsed Power Transistor 650 W Peak, 1200-1400 MHz, 300 µs Pulse, 10% Duty

Features

- GaN on SiC Depletion-Mode Transistor Technology
- Internally Matched
- Common-Source Configuration
- Broadband Class AB Operation
- RoHS* Compliant and 260°C Reflow Compatible
- +50 V Typical Operation
- MTTF = 600 Years (T_J < 200 °C)

Applications

• L-Band pulsed radar.

Description

The MAGX-001214-650L0x is a gold-metalized matched Gallium Nitride (GaN) on Silicon Carbide (SiC) RF power transistor optimized for pulsed L-Band radar applications. Using state of the art wafer fabrication processes, these high performance transistors provide high gain, efficiency, bandwidth, and ruggedness over a wide bandwidth for today's demanding application needs. High breakdown voltages allow for reliable and stable operation under more extreme mismatch load conditions compared with older semiconductor technologies.

MAGX-001214-650L00

Ordering Information

Part Number	Description
MAGX-001214-650L00	GaN Transistor
MAGX-L21214-650L00	1200-1400 MHz Evaluation Board

Typical RF Performance Under Standard Operating Conditions, Pout = 650 W (Peak)

Freq. (MHz)	P _{IN} (W)	Gain (dB)	I _D (A)	Eff. (%)	RL (dB)	Droop (dB)	+1dB OD (W)	VSWR-S (3:1)
1200	8.7	18.8	21.3	61.0	-13.9	0.2	717	S
1250	8.5	18.9	22.0	58.9	-13.8	0.3	726	S
1300	8.0	19.1	22.4	57.8	-13.5	0.3	724	S
1350	7.0	19.7	21.8	59.7	-15.8	0.3	723	S
1400	7.0	19.7	21.1	61.4	-15.0	0.2	697	S

* Restrictions on Hazardous Substances, European Union Directive 2002/95/EC.

1

M/A-COM Technology Solutions Inc. (MACOM) and its affiliates reserve the right to make changes to the product(s) or information contained herein without notice. Visit www.macom.com for additional data sheets and product information.

МАСОМ

Rev. V3







GaN on SiC HEMT Pulsed Power Transistor 650 W Peak, 1200-1400 MHz, 300 µs Pulse, 10% Duty

Rev. V3

Electrical Specifications: Freq. = 1200 - 1400 MHz, T_A = 25°C

Parameter	Test Conditions	Symbol	Min.	Тур.	Max.	Units
RF Functional Tests						
Peak Input Power		P _{IN}	-	7.5	10.3	W
Power Gain	V _{DD} = 50 V, I _{DQ} = 500 mA Pulse Width = 300 µs, Duty Cycle = 10% P _{OUT} = 650 W Peak (65 W avg.)	G _P	18	19.5	-	dB
Drain Efficiency		η _D	55	60	-	%
Pulse Droop		Droop	-	0.3	0.6	dB
Load Mismatch Stability		VSWR-S	-	2:1	-	-
Load Mismatch Tolerance		VSWR-T	-	3:1	-	-

Electrical Characteristics: T_A = 25°C

Parameter	Test Conditions	Symbol	Min.	Тур.	Max.	Units
DC Characteristics		-		1	I	
Drain-Source Leakage Current	V_{GS} = -8 V, V_{DS} = 175 V	I _{DS}	-	1.7	33	mA
Gate Threshold Voltage	$V_{DS} = 5 V, I_{D} = 90 mA$	V _{GS (TH)}	-5	-2.9	-2	V
Forward Transconductance	$V_{DS} = 5 V, I_D = 21 mA$	G _M	16.2	21.7	-	S
Dynamic Characteristics		I		1		
Input Capacitance	Not applicable - Input matched	C _{ISS}	N/A	N/A	N/A	pF
Output Capacitance	$V_{DS} = 50 V, V_{GS} = -8 V,$	C _{OSS}	-	55	-	pF
Reverse Transfer Capacitance	Freq. = 1 MHz	C _{RSS}	-	5.5	-	pF

M/A-COM Technology Solutions Inc. (MACOM) and its affiliates reserve the right to make changes to the product(s) or information contained herein without notice. Visit www.macom.com for additional data sheets and product information.



GaN on SiC HEMT Pulsed Power Transistor 650 W Peak, 1200-1400 MHz, 300 µs Pulse, 10% Duty

Rev. V3

Absolute Maximum Ratings^{1,2,3}

Parameter	Limit
Drain Voltage (V _{DD})	+65 V
Gate Voltage (V _{GG})	-8 to 0 V
Drain Current (I _{DD})	27 A
Input Power ⁴ (P _{IN})	P _{IN} (nominal) + 3 dB
Operating Junction Temperature ⁵	250°C
Peak Pulsed Power Dissipation at 85°C	700 W
Operating Temperature Range	-40 to +85°C
Storage Temperature Range	-65 to +150°C
ESD Min Charged Device Model (CDM)	1300 V
ESD Min Human Body Model (HBM)	4000 V

1. Exceeding any one or combination of these limits may cause permanent damage to this device.

2. MACOM does not recommend sustained operation near these survivability limits.

3. For saturated performance it is recommended that the sum of ($3 * V_{DD} + |V_{GG}|$) < 175 V.

4. Input Power Limit is +3 dB over nominal drive required to achieve P_{OUT} = 650 W.

5. Operating junction temperature is measured with infrared (IR) microscope. Junction temperature directly affects a device's MTTF and should be kept as low as possible to maximize lifetime.

• MTTF = 5.3×10^6 hours (T_J < 200°C) • MTTF = 6.8×10^4 hours (T_J < 250°C)

Thermal Characteristics

Parameter	Test Conditions	Symbol	Typical	Units
Thermal Resistance	T_{C} = 70°C, V_{DD} = 50 V, I_{DQ} = 500 mA, P_{OUT} = 650 W Pulse Width = 300 µs, Duty Cycle = 10%	Θ _{JC}	0.25	°C/W

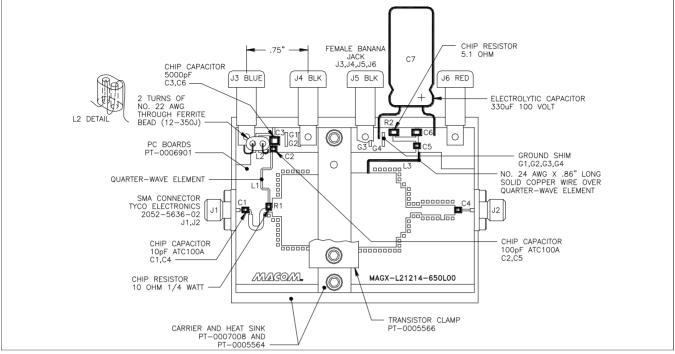
M/A-COM Technology Solutions Inc. (MACOM) and its affiliates reserve the right to make changes to the product(s) or information contained herein without notice. Visit www.macom.com for additional data sheets and product information.



GaN on SiC HEMT Pulsed Power Transistor 650 W Peak, 1200-1400 MHz, 300 µs Pulse, 10% Duty

Rev. V3

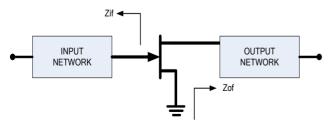
Test Fixture Assembly



Contact factory for gerber file or additional circuit information.

Test Fixture Impedances

F (MHz)	Z _{IF} (Ω)	Z _{OF} (Ω)
1200	0.8 - j0.9	1.4 + j0.2
1250	0.8 - j0.7	1.4 + j0.2
1300	0.7 - j0.6	1.4 + j0.1
1350	0.7 - j0.4	1.2 + j0.1
1400	0.7 - j0.2	1.1 + j0.2



Contact factory for gerber file or additional circuit information.

4

Correct Device Sequencing

Turning the device ON

- 1. Set V_{GS} to the pinch-off (V_P), typically -5 V.
- 2. Turn on V_{DS} to nominal voltage (50 V).
- 3. Increase V_{GS} until the I_{DS} current is reached.
- 4. Apply RF power to desired level.

Turning the device OFF

- 1. Turn the RF power off.
- 2. Decrease V_{GS} down to V_{P} .
- 3. Decrease V_{DS} down to 0 V.
- 4. Turn off V_{GS.}

M/A-COM Technology Solutions Inc. (MACOM) and its affiliates reserve the right to make changes to the product(s) or information contained herein without notice. Visit <u>www.macom.com</u> for additional data sheets and product information.



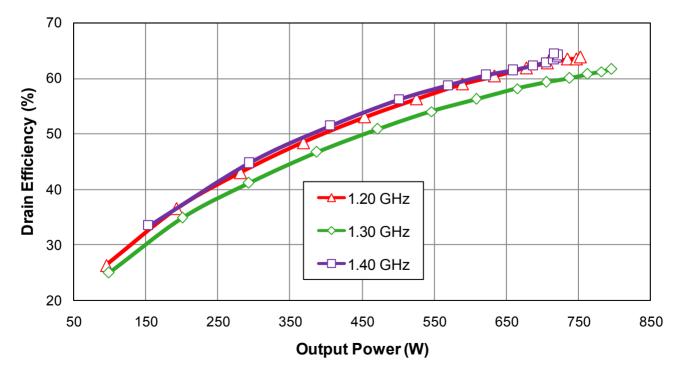
Rev. V3

GaN on SiC HEMT Pulsed Power Transistor 650 W Peak, 1200-1400 MHz, 300 µs Pulse, 10% Duty

850 750 650 **Output Power (W)** 550 450 -____ 1.20 GHz 350 250 150 50 1.0 3.0 5.0 7.0 9.0 11.0 13.0 15.0 Input Power (W)

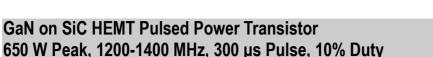
RF Power Transfer Curve (Output Power vs. Input Power)

RF Power Transfer Curve (Drain Efficiency vs. Output Power)

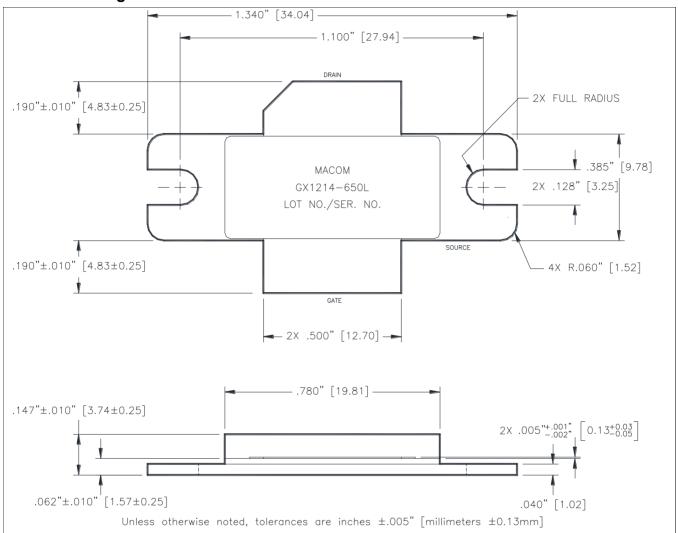


5

M/A-COM Technology Solutions Inc. (MACOM) and its affiliates reserve the right to make changes to the product(s) or information contained herein without notice. Visit www.macom.com for additional data sheets and product information.



Outline Drawing MAGX-001214-650L00



Rev. V3







GaN on SiC HEMT Pulsed Power Transistor 650 W Peak, 1200-1400 MHz, 300 µs Pulse, 10% Duty

Rev. V3

M/A-COM Technology Solutions Inc. All rights reserved.

Information in this document is provided in connection with M/A-COM Technology Solutions Inc ("MACOM") products. These materials are provided by MACOM as a service to its customers and may be used for informational purposes only. Except as provided in MACOM's Terms and Conditions of Sale for such products or in any separate agreement related to this document, MACOM assumes no liability whatsoever. MACOM assumes no responsibility for errors or omissions in these materials. MACOM may make changes to specifications and product descriptions at any time, without notice. MACOM makes no commitment to update the information and shall have no responsibility whatsoever for conflicts or incompatibilities arising from future changes to its specifications and product descriptions. No license, express or implied, by estoppels or otherwise, to any intellectual property rights is granted by this document.

THESE MATERIALS ARE PROVIDED "AS IS" WITHOUT WARRANTY OF ANY KIND, EITHER EXPRESS OR IMPLIED, RELATING TO SALE AND/OR USE OF MACOM PRODUCTS INCLUDING LIABILITY OR WARRANTIES RELATING TO FITNESS FOR A PARTICULAR PURPOSE, CONSEQUENTIAL OR INCIDENTAL DAMAGES, MERCHANTABILITY, OR INFRINGEMENT OF ANY PATENT, COPYRIGHT OR OTHER INTELLECTUAL PROPERTY RIGHT. MACOM FURTHER DOES NOT WARRANT THE ACCURACY OR COMPLETENESS OF THE INFORMATION, TEXT, GRAPHICS OR OTHER ITEMS CONTAINED WITHIN THESE MATERIALS. MACOM SHALL NOT BE LIABLE FOR ANY SPECIAL, INDIRECT, INCIDENTAL, OR CONSEQUENTIAL DAMAGES, INCLUDING WITHOUT LIMITATION, LOST REVENUES OR LOST PROFITS, WHICH MAY RESULT FROM THE USE OF THESE MATERIALS.

MACOM products are not intended for use in medical, lifesaving or life sustaining applications. MACOM customers using or selling MACOM products for use in such applications do so at their own risk and agree to fully indemnify MACOM for any damages resulting from such improper use or sale.

7

M/A-COM Technology Solutions Inc. (MACOM) and its affiliates reserve the right to make changes to the product(s) or information contained herein without notice. Visit www.macom.com for additional data sheets and product information.

X-ON Electronics

Largest Supplier of Electrical and Electronic Components

Click to view similar products for RF Development Tools category:

Click to view products by MACOM manufacturer:

Other Similar products are found below :

MAAP-015036-DIEEV2 EV1HMC1113LP5 EV1HMC252AQS24 EV1HMC6146BLC5A EV1HMC637ALP5 EVAL01-HMC1048LC3B EVAL01-HMC661LC4B EVAL-ADF7020-1DBZ4 EVAL-ADF7020-1DBZ5 EVAL-ADF7020-1DBZ6 EVAL-ADF7020-1DBZ8 EVAL-ADF7021DB9Z EVAL-ADF7021DBJZ EVAL-ADF7021DBZ2 EVAL-ADF7021DBZ6 EVAL-ADF7021-NDBZ2 EVAL-ADF7021-VDB3Z EVAL-ADF7023DB3Z EVAL-ADF7023-JDB3Z EVAL-ADF70XXEKZ1 EVAL-ADF7241DB1Z F0440EVBI F1241EVBI F1423EVB-DI F1423EVB-SI F1701EVBI F1751EVBI F2250EVBI MICRF219A-433 EV 122410-HMC686LP4E AD6679-500EBZ 126223-HMC789ST89E ADL5363-EVALZ ADL5369-EVALZ 130437-HMC1010LP4E 131352-HMC1021LP4E 131372-HMC951LP4E 130436-HMC1010LP4E DEMOBOARD-U2790B ATR2406-PNQW EKIT01-HMC1197LP7F Si4705-D60-EVB Si4835-Demo LMV228SDEVAL SKYA21001-EVB SMP1331-08-EVB EV1HMC618ALP3 EV1HMC641ALC4 EV1HMC8410LP2F EVAL_PAN4555ETU